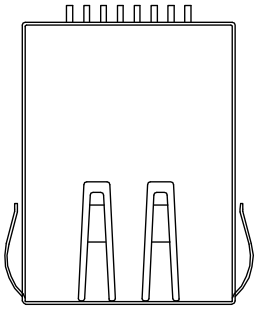
REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.03.24	阿树

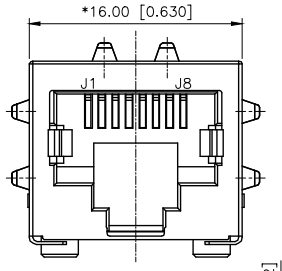


TOP VIEW

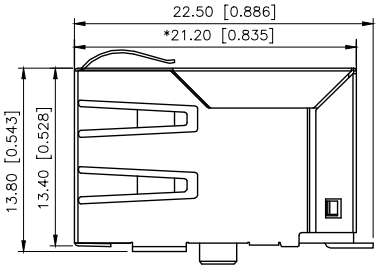
MATERIAL 材料:
- HOUSING 外壳: LCP,UL94V-0,BLACK.
- TERMINALS BRACKET 端子支架: LCP,UL94V-0,BLACK.
- SHIELD 保护物: C2680,T=0.20MM,NICKEL PLATING ON ALL AREA.
- TERMINAL 端子: PHOSPHOR BRONZE C5210,T=0.35MM, GOLD PLATING ON CONTACT AREA.

MECHANICAL 机械:
- DURABILITY 耐用性: 750 CYCLES MIN.
- MATING FORCE 配合力: 30N MAX.
- OPERATING TEMPERATURE 工作温度: -40°C~+85°C.
- STORAGE TEMPERATURE 储存温度: -40°C~+85°C.
- ALL CRITICAL DIMENSIONS WITH "*"

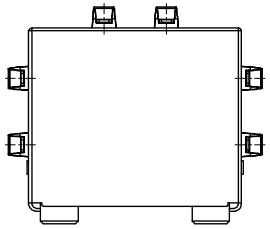
ELECTRICAL电气:
1. Turn ratio 匝数比:1~2:J1~J2=1CT:1CT(±2%)
 3~6:J3~J6=1CT:1CT(±2%)
2. OCL 已占搭载量:350uH Min.at 100KHz 100mV 8mA DC.
3. Insertion Loss 插入损耗: -1.0 dB Max 1~100MHz
4. Return loss 回程损耗: -20dB Min 1~10MHz
 -16dB Min 10~30MHz
 -12dB Min 30~60MHz
 -10dB Min 60~80MHz
5. Cross talk 声道串扰: -40dB Min 1~30MHz;
 -35dB Min 30~60MHz;
 -30dB Min 60~100MHz;
6. CMR 共模抑制: -30dB Min 1~100MHz;
7. Hi-Pot 耐压测试:1500V AC & 2250V DC 6S
 1mA PRI TO SEC



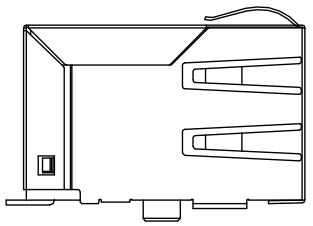
FRONT VIEW



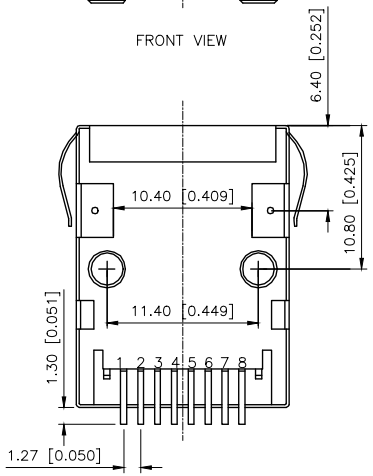
RIGHT SIDE VIEW



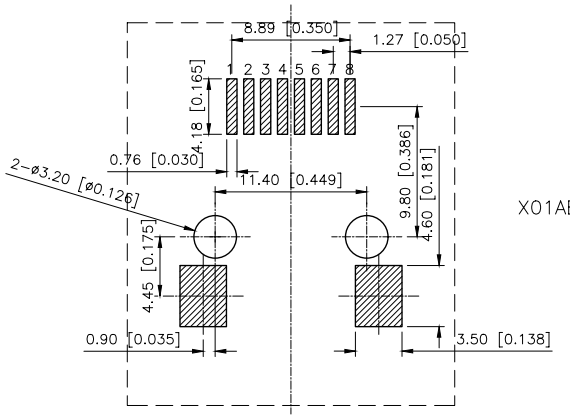
BACK VIEW



LEFT SIDE VIEW



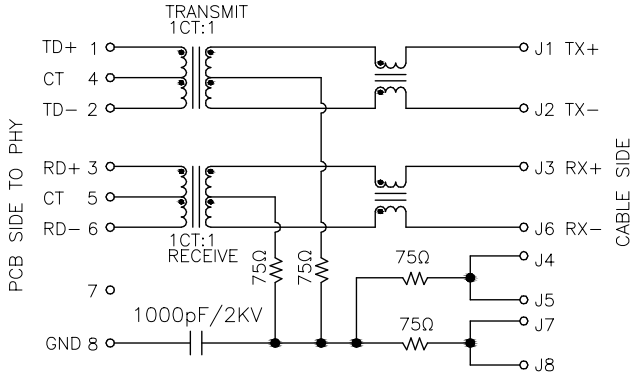
BOTTOM VIEW



RECOMMENDED PCB LAYOUT
VIEWED FROM COMPONENT SIDE

X01AB002HWGS4

1:Au=1U"
3:Au=3U"
4:Au=6U"
5:Au=15U"
6:Au=30U"



AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERAuCES	

XKB Connection 星创

DESIGN	阿树	VIEW:	MODEL TYPE: RJ JACK
CHECKED		UNIT: mm/in	PART NO.: X01AB002HWGS4
APPROVED		SIZE: A4	DWG NO.: X-X01AB002HWGS4

XKB INDUSTRIAL PRECISION CO.,LIMITED

SCALE	PAGE	REVISION
N/A	1/1	A1

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